

Bill of Materials

TI DESIGNS

TIPD124: Single-Supply Full Wave Rectifier

Item #	Quantity	Designator	Value	Description	Manufacturer	Manufacturer Part Number	Supplier Part Number
1	1	C1	4.7uF	CAP, CERM, 4.7uF, 25V, +/-10%, X7R, 1206	TDK	C3216X7R1E475K	445-1606-1-ND
2	2	C2, C8	22uF	CAP, CERM, 22uF, 16V, +/-20%, X7R, 1210	TDK	C3225X7R1C226M	445-3955-1-ND
3	1	C3	10uF	CAP, TANT, 10uF, 50V, +/-10%, 0.4 ohm, 7343-43 SMD	AVX	TPSE106K050R0400	478-3361-1-ND
4	2	C4, C6	0.1uF	CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0805	MuRata	GRM21BR71H104KA01L	490-1666-1-ND
5	1	C5	10uF	CAP, CERM, 10uF, 25V, +/-10%, X7R, 1206	MuRata	GRM31CR71E106KA12L	81-GRM31CR71E106KA12
6	1	C7	100pF	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0805	MuRata	GRM2165C1H101JA01D	490-1615-1-ND
7	1	C9	0.47uF	CAP, CERM, 0.47uF, 16V, +/-10%, X7R, 0805	AVX	0805YC474KAT2A	478-1403-1-ND
8	1	C10	1000pF	CAP, CERM, 1000pF, 100V, +/-5%, C0G/NP0, 0805	AVX	08051A102JAT2A	478-1290-1-ND
9	2	C11, C14	DNI	DNI	DNI	DNI	DNI
10	3	C12, C15, C17	100pF	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603	Kemet	C0603C101J5GACTU	399-1061-1-ND
11	3	C13, C16, C18	0.1uF	CAP, CERM, 0.1uF, 25V, +/-10%, X7R, 0603	MuRata	GRM188R71E104KA01D	490-1524-1-ND
12	1	D1		Diode, Ultrafast, 100V, 0.15A, SOD-123	Diodes Inc.	1N4148W-7-F	1N4148W-FDICT-ND
13	1	J1		Standard Banana Jack, Uninsulated, 5.5mm	Keystone	575-4	575-4K-ND
14	1	J2		Standard Banana Jack, Uninsulated, 5.5mm	Keystone	575-4	575-4K-ND
15	2	J3, J4		Right Angle BNC Connector	TE Connectivity	1-1634612-0	571-1-1634612-0
16	3	R1, R2, R3	1.00k	RES, 1.00k ohm, 0.1%, 0.1W, 0603	Yageo America	RT0603BRD071KL	603-RT0603BRD071KL
17	1	R4	49.9	RES 49.9 OHM 0.20W 0.1% 0805	Vishay Thin Film	PAT0805E49R9BST1	PAT49.9BCT-ND

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